

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)  
 Contact Info: [ti.com/support](http://ti.com/support)  
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB  
 Created on: 05/06/2022

Details for "TLC27M2BCDG4"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
TLC27M2BCDG4	NIPDAU	Level-1-260C-UNLIM	TI TAIWAN A/T	D   8	3.91x4.9x1.58	85.2

\*Total Device Mass  
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
<b>Bond Wire</b>							
Other Nonferrous Metals and Alloys	Yttrium	7440-65-5	0.000001	0.001329	13	0.000001	0
Precious Metals	Gold	7440-57-5	0.075257	99.997343	999973	0.088329	883
Precious Metals	Silver	7440-22-4	0.000001	0.001329	13	0.000001	0
Sub-Total			0.075259	100	1000000	0.088332	883
<b>Die Attach Adhesive</b>							
Precious Metals	Silver	7440-22-4	0.626729	80.000026	800000	0.735595	7356
Thermoplastics	Epoxy	85954-11-6	0.156682	19.999974	200000	0.183898	1839
Sub-Total			0.783411	100	1000000	0.919493	9195
<b>Lead Frame</b>							
Copper and Its Alloys	Copper	7440-50-8	24.25509	97.41	974100	28.468304	284683
Copper and Its Alloys	Iron	7439-89-6	0.5976	2.4	24000	0.701406	7014
Copper and Its Alloys	Phosphorus	7723-14-0	0.00747	0.03	300	0.008768	88
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.00747	0.03	300	0.008768	88
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.00747	0.03	300	0.008768	88
Zinc and Its Alloys	Zinc	7440-66-6	0.0249	0.1	1000	0.029225	292
Sub-Total			24.9	100	1000000	29.225238	292252
<b>Lead Frame Plating</b>							
Nickel and Its Alloys	Nickel	7440-02-0	0.355273	95.119946	951199	0.416985	4170
Precious Metals	Gold	7440-57-5	0.002913	0.77992	7799	0.003419	34
Precious Metals	Palladium	7440-05-3	0.015314	4.100134	41001	0.017974	180
Sub-Total			0.3735	100	1000000	0.438379	4384
<b>Mold Compound</b>							
Other Inorganic Materials	Fused Silica	60676-86-0	49.726204	88	880000	58.363861	583639
Other Plastics and Rubber	Carbon Black	1333-86-4	0.169521	0.3	3000	0.198968	1990
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.310789	0.55	5500	0.364774	3648
Thermoplastics	Epoxy	85954-11-6	6.300536	11.15	111500	7.394966	73950
Sub-Total			56.50705	100	1000000	66.322569	663226
<b>Semiconductor Device</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	2.561113	100	1000000	3.005989	30060
Sub-Total			2.561113	100	1000000	3.005989	30060
<b>Total</b>			85.200333			100	1000000

**Important Note**  
 The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.  
 The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.  
[See Glossary of Terms for more details.](#)

**Important Part Information**  
 There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSi or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

**Product Content Methodology**  
[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

**Material Declaration Certificate for Semiconductor IC Packaged Products**

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

**Important Information/Disclaimer**

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

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[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to [www.ti.com/ecoinfo](http://www.ti.com/ecoinfo)  
 Created on: 05/06/2022

**RoHS:** Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

**RoHS Exempt:** Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

**Green:** Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.